



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-06-05
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	R2{9*OD8LA52	A	SHENZHEN B/E	2015-06-05
Amount	UoM	Unit type	ST ECOPACK Grade	
1380	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 7.2, 4.5	3	GULL WING	
Comment	Package: H2PAK HC 2-3 Leads, MD valid for CP: STH275N8F7-2AG			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	R2(9*OD8LA52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	20.903	mg	supplier	die	Silicon (Si)	7440-21-3		20.267	mg	969574	14686
				supplier	metallization	Aluminium (Al)	7429-90-5		0.189	mg	9042	137
				supplier	metallization	Titanium (Ti)	7440-32-6		0.037	mg	1770	27
				supplier	Passivation	Silicon Oxide	7631-86-9		0.215	mg	10286	156
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.011	mg	526	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.145	mg	6937	105
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.007	mg	335	5
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.032	mg	1531	23
				supplier	alloy	Copper (Cu)	7440-50-8		843.710	mg	991899	611384
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		1.696	mg	1994	1229
Leadframe	Copper & its alloys	850.601	mg	supplier	alloy	Cobalt (Co)	7440-48-4		2.374	mg	2791	1720
				supplier	metallization	Nickel (Ni)	7440-02-0		2.804	mg	3296	2032
				supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	20	12
				supplier	alloy	Copper (Cu)	7440-50-8		843.710	mg	991899	611384
Soft solder	Solder	18.593	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	17.756	mg	954983	12867
				supplier	solder	Silver (Ag)	7440-22-4		0.465	mg	25009	337
				supplier	solder	Tin (Sn)	7440-31-5		0.372	mg	20008	270
Bonding wires	Other inorganic materials	0.129	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.128	mg	992248	93
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	7752	1
				supplier	Ribbon	Aluminium (Al)	7429-90-5		18.590	mg	1000000	13471
Bonding Ribbons	Other Nonferrous metals & alloys	18.590	mg	supplier	Encapsulation	Other Organic Materials	467.450	mg	376.765	mg	806001	273018
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		32.722	mg	70001	23712
				supplier	mold compound	Phenol resin	9003-35-4		18.698	mg	40000	13549
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		28.047	mg	60000	20324
				supplier	mold compound	Antimony Trioxide	1309-64-4		5.609	mg	11999	4064
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		3.272	mg	7000	2371
connections coating	Solder	3.734	mg	supplier	mold compound	Carbon black	1333-86-4		2.337	mg	4999	1693
				supplier	solder alloy	Tin (Sn)	7440-31-5		3.734	mg	1000000	2706